

HB05

Manual wire bonder for wedge and ball applications



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Compact Design & Intuitive Control
 The practical design makes our bonder very easy to use
- 
4" TFT Display & Multi Button
 Fast and easy control of all bond parameters
- 
Storage For 20 Parameter Sets
 Easy setting recall for working on different applications
- 
Simple Change Between Ball & Wedge Bonding
 1. change bond tool 2. thread the wire 3. select bond mode
- 
Deep & Wide Bond Access
 Ample work space due to special bond head design
- 
Electronic Wire Clamp - Up & Down Movement
 Precise tail length control
- 
Stud Bump Bonding
 Ball bonders equipped with bump bonding mode
- 
Motorized Wire Spool (Option)
 For large wire spools and consistent looping

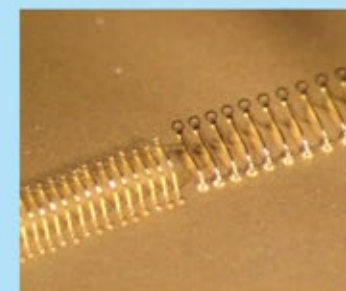
Bonders "Made in Germany"

Relying on over 20 years wire bonding knowhow, TPT designs and manufactures a complete range of manual and semi automatic wire bonder machines.

TPT is a privately owned company, with the goal to provide the highest quality wire bonding equipment.

Based in Munich, TPT draws strength from Germany's high technology region.

TPT bonders are used in many leading Universities, Institutes and Semiconductor, Aerospace & Medical device companies throughout the world.



Wedge & ball bonds



TFT Display



Bond head